NITROGEN IMPLANTATION IN N-TYPE AND P-TYPE SILICON

by

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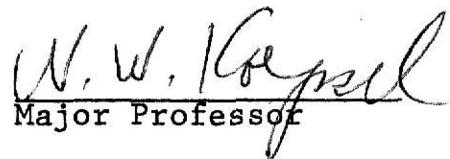

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